ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C64M16D3LD-10BCN / AS4C64M16D3LD-12BCN			
Part Weight:		**157.03mg**			
Item	**Material**	**Weight (mg)**	**Content**	**CAS No.**	**Percentage %**
1	Epoxy Molding Compound	73.5500	Carbon Black	1333-86-4	0.40%
			Epoxy Resin	Trade secret	5.00%
			Hardener	Trade secret	5.00%
			Silica	60676-86-0	89.60%
2	Die Attach	4.0720	2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	39.50%
			Butadiene, acrylonitrile polymer, carboxy-terminat	68610-41-3	29.50%
			Isodecyl alcohol, ethoxylated~	61827-42-7	8.00%
			Silica Filler	112926-00-8	22.50%
			tert-butyl peroxyneodecanoate	26748-41-4	0.50%
3	Substrate	36.6600	Naphtha (petroleum), heavy aromatic	64742-94-5	3.50%
			TALC (CONTAINING NO ASBESTOS FIBRES)	14807-96-6	11.00%
			Copper	7440-50-8	25.00%
			Nickel	7440-02-0	3.00%
			Gold	7440-57-5	0.50%
			Continuous FilamentFiber Glass	65997-17-3	16.75%
			Cured thermosettingresin (includinginorganic filler)	9003-01-4	25.05%
			Epoxy resin	115254-47-2	3.52%
			Barium Sulfate	7727-43-7	7.20%
			Dipropylene glycolmonomethyl ether	34590-94-8	3.84%
			Morpholine derivative	110-91-8	0.64%
4	Solder Ball	32.6400	Copper (Cu)	7440-50-8	0.50%
			Silver (Ag)	7440-22-4	3.00%
			Tin (Sn)	7440-31-5	96.50%
5	Bond Wire	2.8680	Gold (Au)	7440-57-5	99.00%
			Others	N/A	1.00%
6	Chip	7.2400	Si	7440-21-3	99.00%
			Others	NA	1.00%
Total		157.0300			mg

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Fax: 425-896-8628 Alliance Memory Inc. reserves the right to change products or specification without notice